

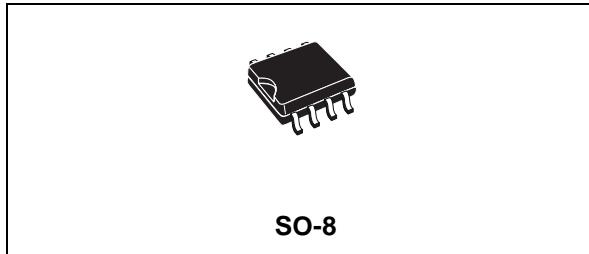


# STS2DNFS30L

## N-CHANNEL 30V - 0.09Ω - 3A SO-8 STripFET™ II MOSFET PLUS SCHOTTKY RECTIFIER

PRELIMINARY DATA

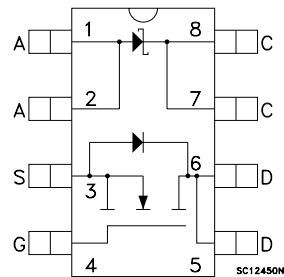
MAIN PRODUCT CHARACTERISTICS			
MOSFET	V <sub>DSS</sub>	R <sub>D(on)</sub>	I <sub>D</sub>
	30 V	< 0.11 Ω	3 A
SCHOTTKY	I <sub>F(AV)</sub>	V <sub>RRM</sub>	V <sub>F(MAX)</sub>
	1 A	30 V	0.46 V



### DESCRIPTION

This product associates the latest low voltage STripFET™ in n-channel version to a low drop Schottky diode. Such configuration is extremely versatile in implementing a large variety of DC-DC converters for printers, portable equipment, and cellular phones.

### INTERNAL SCHEMATIC DIAGRAM



### MOSFET ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	30	V
V <sub>DGR</sub>	Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)	30	V
V <sub>GS</sub>	Gate-source Voltage	± 15	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 25°C	3	A
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 100°C	1.9	A
I <sub>DM</sub> (●)	Drain Current (pulsed)	12	A
P <sub>TOT</sub>	Total Dissipation at T <sub>C</sub> = 25°C	2	W

### SCHOTTKY ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	30	V
I <sub>F(RMS)</sub>	RMS Forward Current	7	A
I <sub>F(AV)</sub>	Average Forward Current	TL = 135°C δ = 0.5	A
I <sub>FSM</sub>	Surge Non Repetitive Forward Current	tp = 10 ms Sinusoidal	A
I <sub>RSR</sub>	Non Repetitive Peak Reverse Current	tp = 100 μs	A
dv/dt	Critical Rate Of Rise Of Reverse Voltage	10000	V/μs

(●)Pulse width limited by safe operating area

## STS2DNFS30L

---

### THERMAL DATA

R <sub>thj-amb</sub>	(*)Thermal Resistance Junction-ambient MOSFET	62.5	°C/W
R <sub>thj-amb</sub>	(*)Thermal Resistance Junction-ambient SCHOTTKY Maximum	100	°C/W
T <sub>stg</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Junction Temperature	150	°C
(*) Mounted on FR-4 board (Steady State)			

### MOSFET ELECTRICAL CHARACTERISTICS (TCASE = 25 °C UNLESS OTHERWISE SPECIFIED) OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	I <sub>D</sub> = 250 µA, V <sub>GS</sub> = 0	30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max Rating V <sub>DS</sub> = Max Rating, T <sub>C</sub> = 125 °C			1 10	µA µA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 15 V			±100	nA

### ON (1)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250µA	1			V
R <sub>D(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 1.5 A V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 1.5 A		0.09 0.13	0.11 0.15	Ω Ω

### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g <sub>fs</sub> (1)	Forward Transconductance	V <sub>DS</sub> = 15 V , I <sub>D</sub> = 1.5 A		2.5		S
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, f = 1 MHz, V <sub>GS</sub> = 0		121		pF
C <sub>oss</sub>	Output Capacitance			45		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			11		pF

**ELECTRICAL CHARACTERISTICS (CONTINUED)****SWITCHING ON**

<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 15 \text{ V}$ , $I_D = 1.5 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 4.5 \text{ V}$ (see test circuit, Figure 3)		19		ns
$t_r$	Rise Time			20		ns
$Q_g$	Total Gate Charge	$V_{DD} = 24 \text{ V}$ , $I_D = 3 \text{ A}$ ,		4.5	6	nC
$Q_{gs}$	Gate-Source Charge	$V_{GS} = 4.5 \text{ V}$		1.7		nC
$Q_{gd}$	Gate-Drain Charge			0.9		nC

**SWITCHING OFF**

<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$t_{d(off)}$	Turn-off Delay Time	$V_{DD} = 15 \text{ V}$ , $I_D = 1.5 \text{ A}$ ,		12		ns
$t_f$	Fall Time	$R_G = 4.7\Omega$ , $V_{GS} = 4.5 \text{ V}$ (see test circuit, Figure 3)		8		ns

**SOURCE DRAIN DIODE**

<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$I_{SD}$	Source-drain Current				3	A
$I_{SDM}(2)$	Source-drain Current (pulsed)				12	A
$V_{SD}(1)$	Forward On Voltage	$I_{SD} = 3 \text{ A}$ , $V_{GS} = 0$			1.2	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 3 \text{ A}$ , $dI/dt = 100\text{A}/\mu\text{s}$ ,		19		ns
$Q_{rr}$	Reverse Recovery Charge	$V_{DD} = 30 \text{ V}$ , $T_j = 150^\circ\text{C}$ (see test circuit, Figure 5)		8.1		nC
$I_{RRM}$	Reverse Recovery Current			0.85		A

Note: 1. Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %.

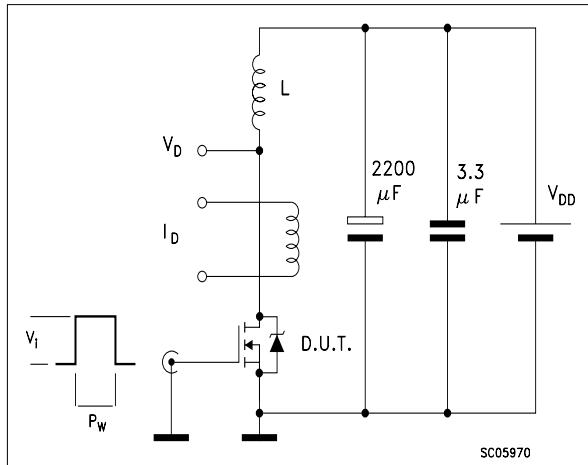
2. Pulse width limited by safe operating area.

**SCHOTTKY STATIC ELECTRICAL CHARACTERISTICS**

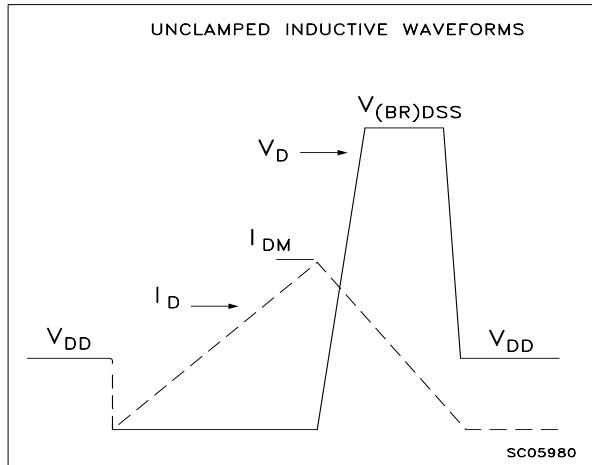
<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$I_R(*)$	Reversed Leakage Current	$T_J = 25^\circ\text{C}$ , $V_R = 30 \text{ V}$ $T_J = 125^\circ\text{C}$ , $V_R = 30 \text{ V}$		1.5	10 10	$\mu\text{A}$ mA
$V_F(*)$	Forward Voltage Drop	$T_J = 25^\circ\text{C}$ , $I_F = 1 \text{ A}$ $T_J = 125^\circ\text{C}$ , $I_F = 1 \text{ A}$		0.37	0.55 0.46	V V

## STS2DNFS30L

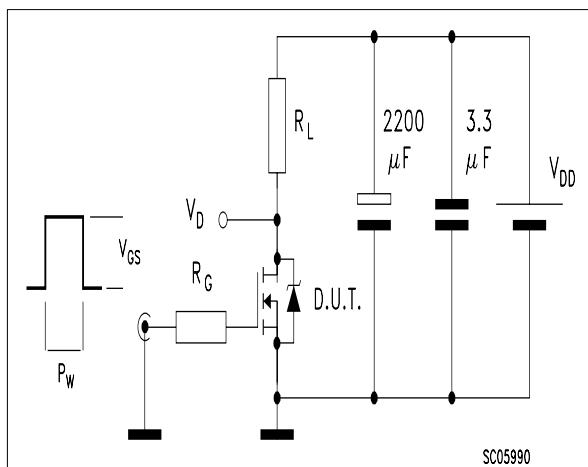
**Fig. 1:** Unclamped Inductive Load Test Circuit



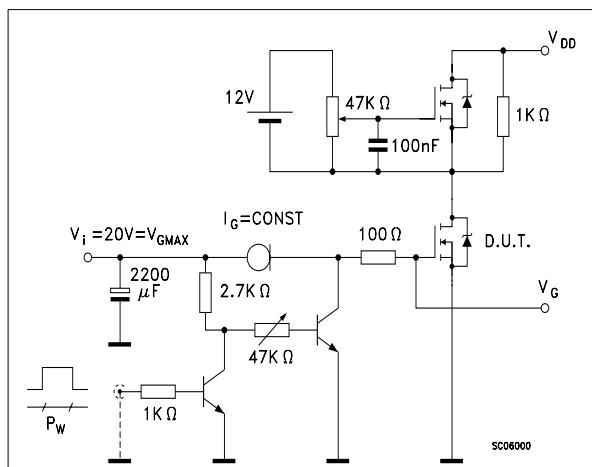
**Fig. 2:** Unclamped Inductive Waveform



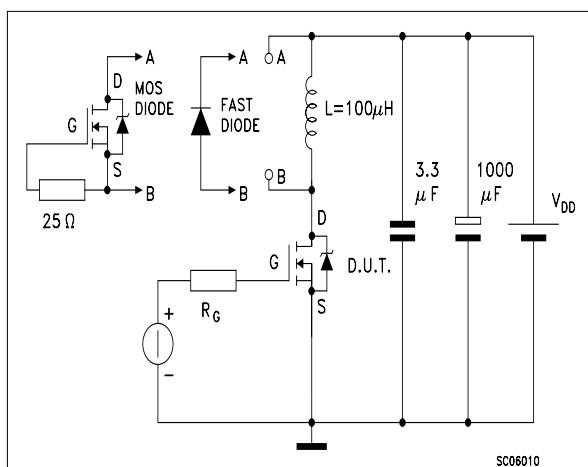
**Fig. 3:** Switching Times Test Circuit For Resistive Load



**Fig. 4:** Gate Charge test Circuit

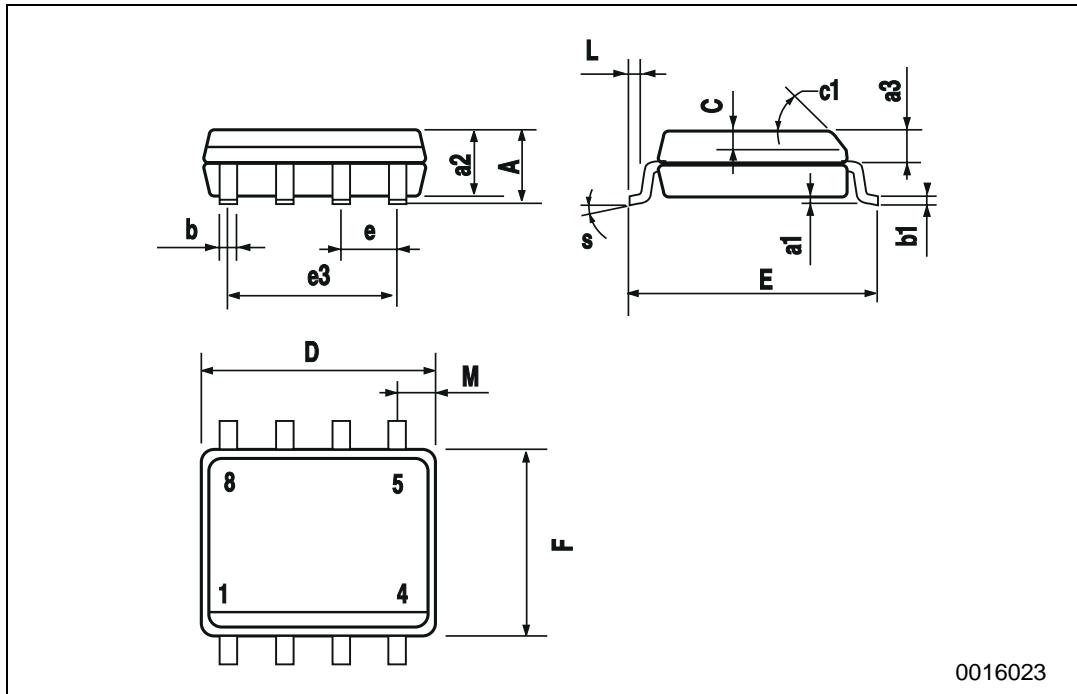


**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times



## SO-8 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
C	0.25		0.5	0.010		0.019
c1		45 (typ.)				
D	4.8		5.0	0.188		0.196
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
M			0.6			0.023
S		8 (max.)				



Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specification mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a trademark of STMicroelectronics

© 2000 STMicroelectronics – Printed in Italy – All Rights Reserved  
STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - China - Finland - France - Germany - Hong Kong - India - Italy - Japan - Malaysia - Malta - Morocco -  
Singapore - Spain - Sweden - Switzerland - United Kingdom - U.S.A.

<http://www.st.com>